



IECQ Certificate of Conformity Capability

IECQ Certificate No.:	IECQ-C BSI 13.0001	Issue No.:	3	Status:	Current
Supersedes:	IECQ-C BSI 13.0001 Issue 2	Issue Date:	2018/01/11	Org Issue:	2013/02/06
CB Reference No.:	030/ICA	Expiration:	2021/01/31		

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 United Kingdom

The organization has developed and implemented procedures and related processes which have been assessed by the IECQ Certification Body issuing this certificate and found to comply with the applicable requirements of the IECQ Approved Component Scheme "Capability Certification" which is in accordance with the Basic Rules IECQ 01 "Rules of Procedure", IECQ 03-1 "IECQ General Requirements for all Schemes" and IECQ 03-3 Annex D "IECQ Approved Components Scheme" of the IEC Quality Assessment System for Electronic Component (IECQ), and in respect of standard(s) or specification(s):

- **IPC-6011 {July 1996}** Generic Performance Specification for Printed Boards
- **IPC-6012C {2010}** Qualification and Performance Specification for Rigid Printed Boards
- **IPC-6013B {January 2009}** Qualification and Performance Specification for Flexible Printed Boards

Process Manual Reference: **BS/IPC/CM01 IECQ 03-3 Annex D**

Details of Components/Assemblies/Materials:

Rigid Multilayer
Flex-Rigid multilayer with through holes
Rigid double-sided with plated through holes
Rigid single & double-sided with plain holes

-- Attached Schedule: 030_ICA scope Issue 3.pdf --

Issued by the Certification Body (CB): BSI

Kitemark Court, Davy Avenue
 Knowlhill, Milton Keynes MK5 8PP
 United Kingdom

Authorized person:
Paul Turner

PT _____



The validity of this certificate is maintained through on-going surveillance audits by the IECQ CB issuing this certificate.
 This Certificate of Conformity may be suspended or withdrawn in accordance with the Rules of Procedure of the IECQ System and its Schemes.
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IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

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Board Types:	Rigid Multilayer (Type 4)	IPC 6012C Class 3*
	Rigid double-sided with plated through holes (Type 2) Rigid single & double-sided with plain holes (Types 1 & 2) Double-Sided boards (Type 2) Single-Sided Boards (Type 1 & 2)	
	Flex-Rigid multilayer with through holes (Type 4)	IPC 6013B Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

Base Materials: Epoxide Woven Glass (IPC4101, 4202, 4203, BS4584)
Polyimide film/polyester film (IPC 4204)
Polytetrafluorethylene (IPC 4103)

Board Size: 495.30 mm x 419.10 mm single/double and multilayer
261.87 mm x 322.33 mm flex-rigid multilayer

Number of Layers: 32 maximum Rigid multilayer
10 maximum Flex-Rigid multilayer

Conductors: 0.050 mm (photomech) Tolerance -0.01+0.03mm
0.10 mm (photomech) Tolerance -0.02 +0.03 mm

Plated-through Hole Diameter: 0.20 mm Minimum Finished hole size
0.80 mm Minimum Finished hole size

Aspect Ratio: 20 : 1 Maximum single and double sided
16.0:1 Maximum multilayer
2.27 : 1 Maximum flex-rigid multilayer

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Finishes: * Hot Air Solder Levelling
Immersion Silver
2.5µm Gold over Copper Edge Contacts
Liquid Photopolymer Solder Resist
Legend; UV or Oven Cured
Solder resist UV cured

Additional: Selective Electroplated Gold (2.5 µm) on Copper
Selective Electroless Gold (0.05 µm) on Copper
Silver, Organic Coating
NemaL1-I

* This finish meets the solderability requirements.

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The BSI logo consists of the lowercase letters 'bsi' in a bold, sans-serif font, with a small red dot above the 'i'.